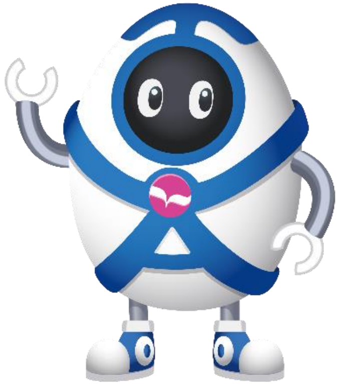
FY2025 Q1
Business Results

August 7, 2025



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FY2025 Q1 Summary

¥100M

Orders	Net Sales	Operating Profit	Ordinary Profit	Net Profit
¥104.3	¥80.8	-¥5.8	-¥7.3	-¥5.3
YoY -20.2%	YoY -39.0%	¥22.1 in FY24 Q1	¥24.2 in FY24 Q1	¥16.9 in FY24 Q1

Orders

・Due to the impact of U.S. tariff policy trends, customers—particularly in “Other Asia” region—continue to take a wait-and-see attitude to investment.
・In China, orders are showing signs of recovery, driven by economic stimulus measures and moves toward in-house semiconductor manufacturing.

Net Sales

・Significant decline due to continued order weakness since the second half of the previous fiscal year, and adjustments in customers’ delivery schedules in certain regions caused by customer-related factors.

Profit

・As net sales did not reach the break-even point, all levels of profit recorded a loss.
・From Q2 onward, we expect to return to profitability, driven by a recovery in net sales.

FY2025 Q1 Consolidated Financial Results

¥100M

	FY2024 1Q Results	FY2025 1Q Results	Variance	YoY
Net Sales	132.5	80.8	-51.7	-39.0%
Operating Profit	22.1	-5.8	-27.9	-
Ordinary Profit	24.2	-7.3	-31.5	-
Net Profit	16.9	-5.3	-22.2	-

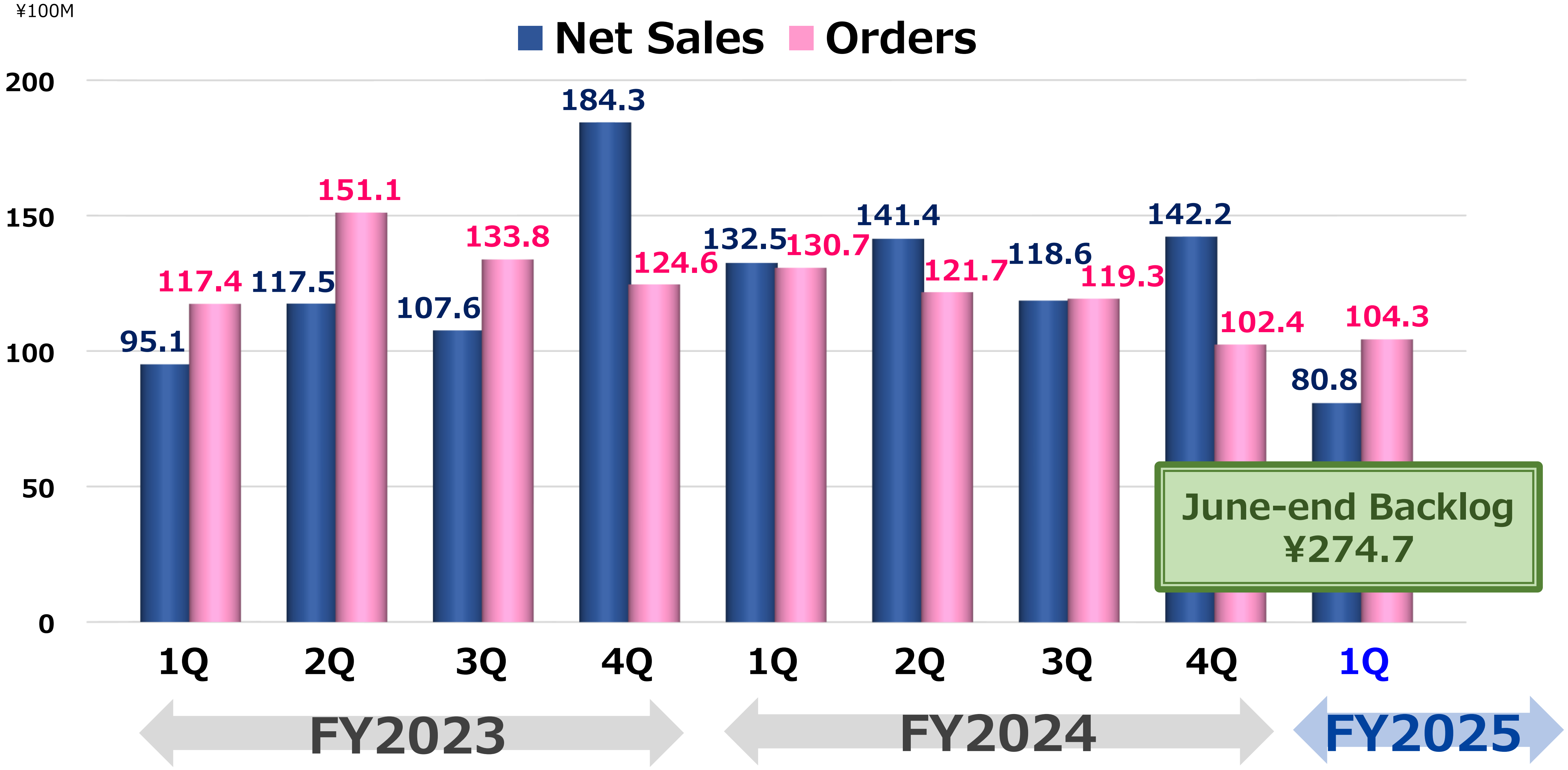
※Net Profit= Profit attributable to owners of parent

FY2025 Q1 Net Sales by Business Segment

¥100M

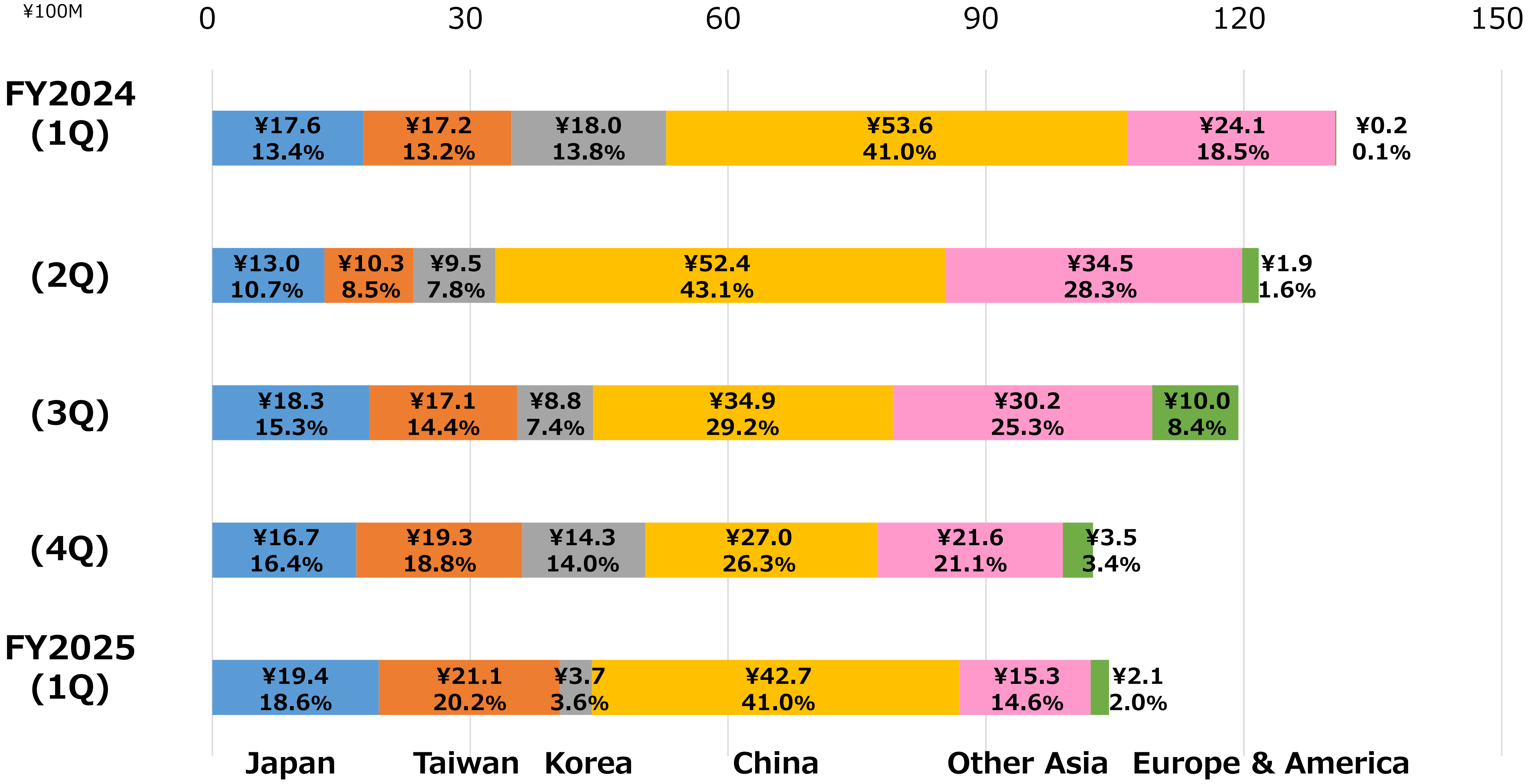
	FY2024 1Q Results	FY2025 1Q Results	Variance	YoY
Net Sales	132.5	80.8	-51.7	-39.0%
Semiconductor	100.6	51.7	-48.9	-48.6%
Medical Device	5.7	5.9	+0.2	+4.3%
New Business	22.0	20.3	-1.7	-7.7%
Laser	4.2	2.8	-1.4	-33.2%

Net Sales and Orders Trend

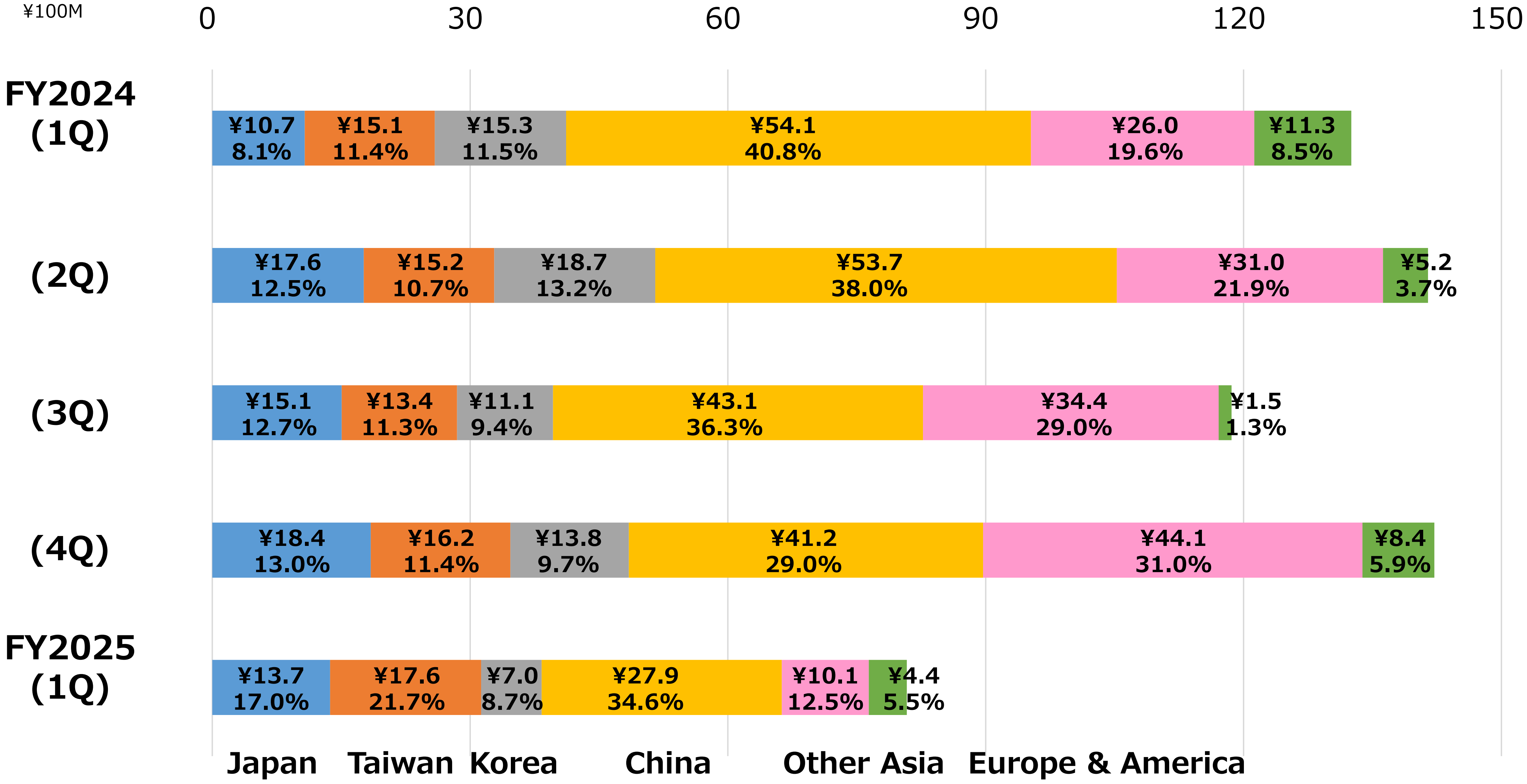


June-end Backlog
¥274.7

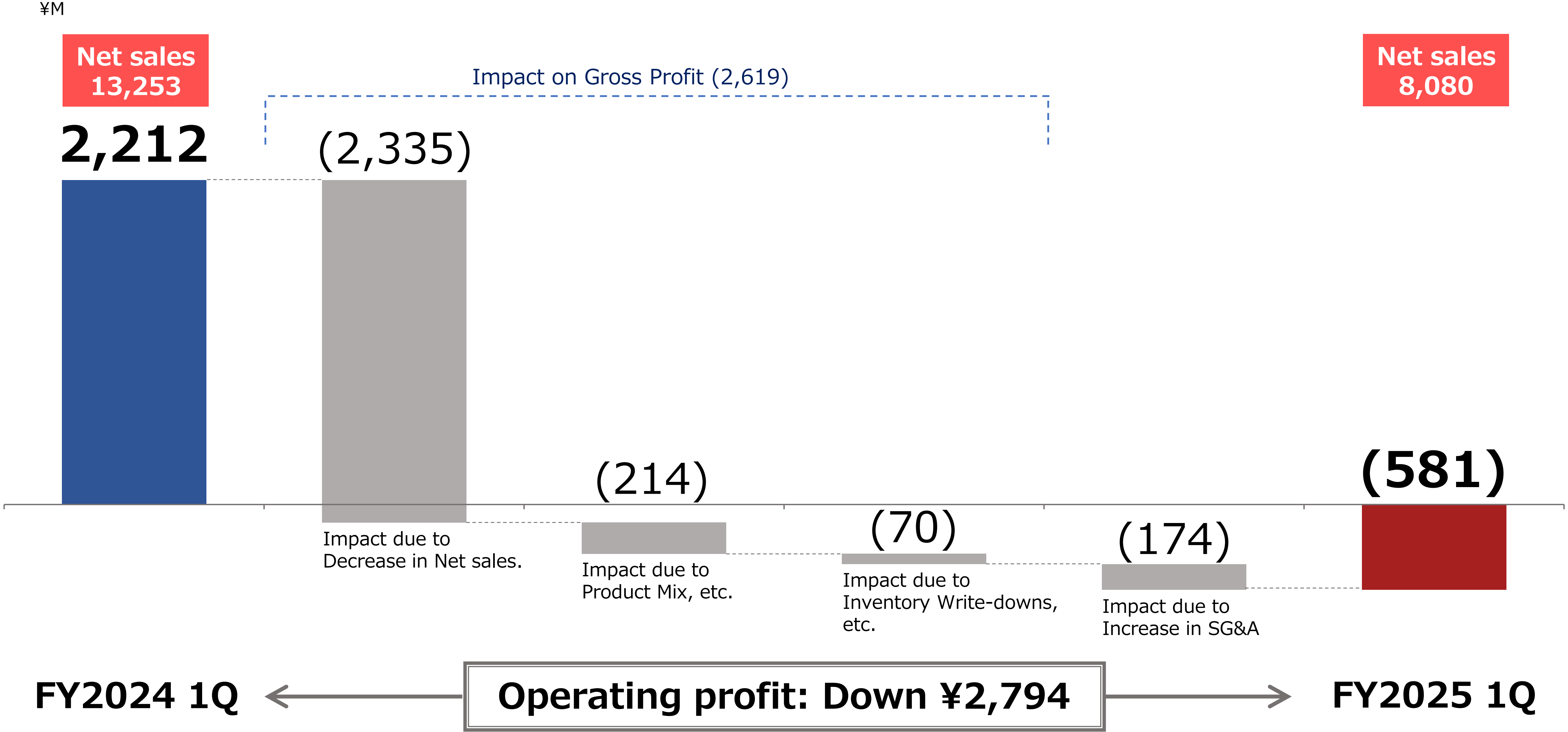
Trend of Regional Order Composition Ratio (Destination-Based)



Trend of Regional Sales Composition Ratio (Destination-Based)



FY2025 Q1 Operating Profit Variance Analysis（YoY)



※Yen amounts are rounded down to millions.

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FY2025 1H Financial Forecast

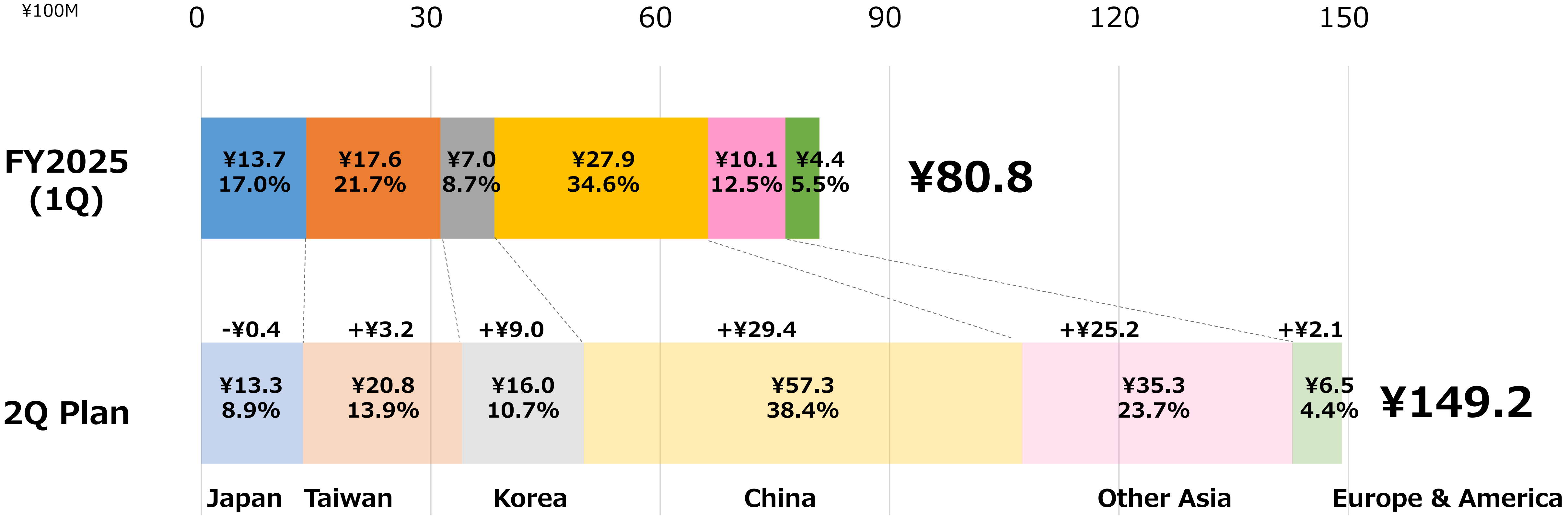
¥100M

	FY2024 1H Results	FY2025 Forecast			Variance	YoY
		1Q Results	2Q	1H		
Net Sales	273.9	80.8	149.2	230.0	-43.9	-16.1%
Operating Profit	52.6	-5.8	22.9	17.1	-35.5	-67.5%
Operating margin	19.2%	-	15.4%	7.4%	-11.8pt	-
Ordinary Profit	52.2	-7.3	24.4	17.1	-35.1	-67.3%
Net Profit	38.2	-5.3	17.3	12.0	-26.2	-68.7%

※Net Profit= Profit attributable to owners of parent

※Initial forecast is **unchanged**.

Regional Trends (Sales Forecast)



| Key Drivers of
| Increase :

| ･Smartphones
| ･Automotive
| ･PCs

| ･Smartphones
| ･Data Centers

| ･Consumer Electronics
| ･Data Centers
| ･Smartphones
| ･Automotive
| ･PCs

| ･Automotive
| ･Consumer Electronics
| ･Industrial Machinery
| ･Smartphones

Regional Trends (Orders)

China

- Orders are showing signs of recovery from Q1, driven by economic stimulus measures. Continued to remain at a high level from Q2 onward.

Taiwan

- Stricter regulations have driven a shift back to Taiwan, leading to a gradual recovery in demand. Demand for PLP for AI applications is also growing.

Korea

- Non-AI memory remains sluggish, while orders for next-generation AI-related equipment are expected from Q2 onward.

Other Asia

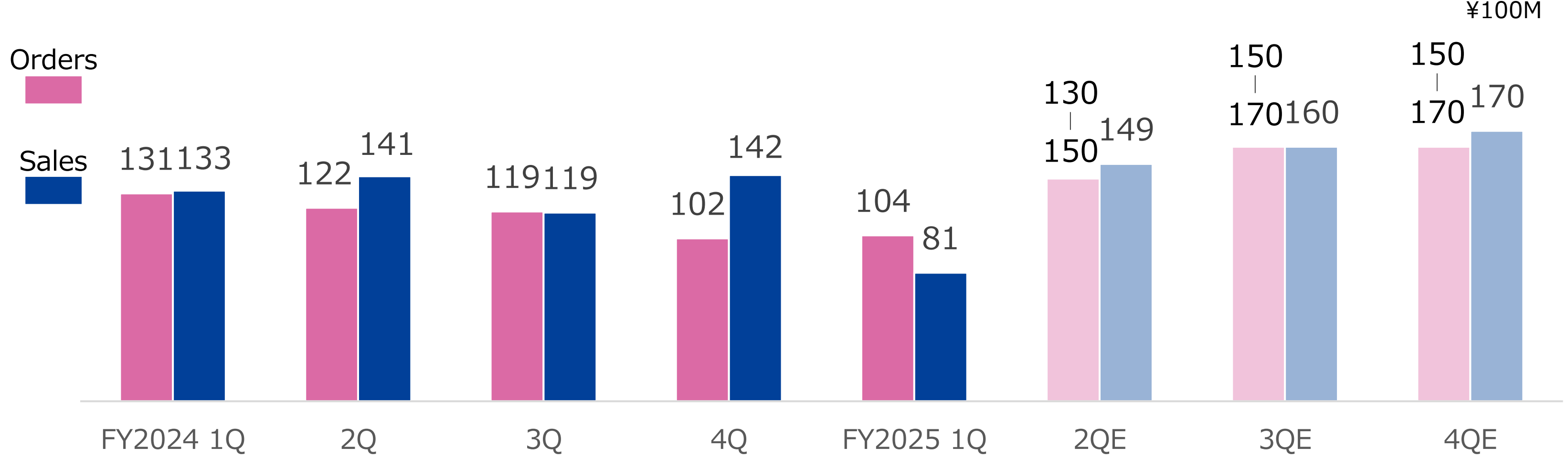
- The wait-and-see attitude on investment due to tariff impacts gradually improved from Q2 onward.

Market Outlook

Market Outlook Going Forward

- For Q2, we expect sales from projects whose deliveries were adjusted from Q1, and the cumulative results for Q2 are expected to progress in line with the sales plan.
- Orders are gradually recovering, and we expect an increase from Q2 through the second half. We also anticipate receiving orders for next-generation generative AI-related equipment from the Q2 onward.

Orders/Sales Forecast



Orders Forecast

¥100M

2Q
¥130–150

3Q
¥150–170

4Q
¥150–170

Profit & Loss Forecast

¥100M

Net Sales	¥560.0
Operating Profit	¥98.0
Ordinary Profit	¥98.0
Net Profit	¥68.6

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FY2025 Forecast

¥100M

	FY2024 Results	FY2025 Forecast			Variance	YoY
		1H	2H	FY		
Net Sales	534.7	230.0	330.0	560.0	+25.2	+4.7%
Operating Profit	88.8	17.1	80.9	98.0	+9.1	+10.4%
Operating margin	16.6%	7.4%	24.5%	17.5%	+0.9pt	-
Ordinary Profit	94.0	17.1	80.9	98.0	+3.9	+4.3%
Net Profit	81.2	12.0	56.6	68.6	-12.6	-15.5%

※Net Profit= Profit attributable to owners of parent

※Initial forecast is **unchanged**.

FY2025 Forecast of Net Sales by Business Segment

¥100M

Changed

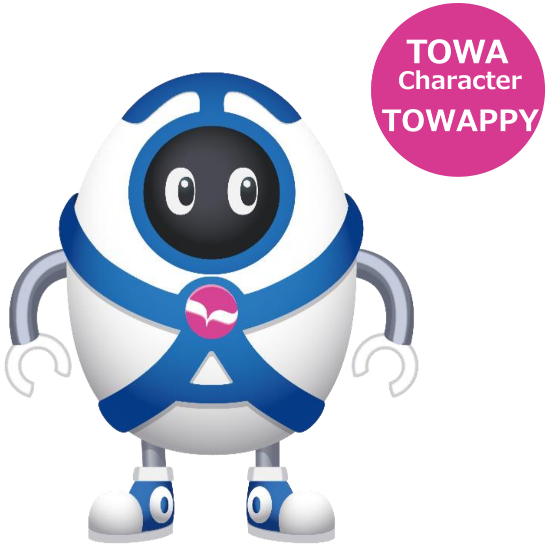
	FY2024 Results	FY2025 Forecast			Variance	YoY
		1H	2H	FY		
Net Sales	534.7	230.0	330.0	560.0	+25.2	+4.7%
Semiconductor	395.3	165.8	251.0	416.8	+21.5	+5.4%
Medical Device	22.6	11.9	12.0	23.9	+1.3	+5.7%
New Business	94.2	45.5	54.0	99.5	+5.3	+5.6%
Laser	22.6	6.8	13.0	19.8	-2.8	-12.4%

TOWA Vision 2032

「To the top of the world with change」

《Contact》
TOWA CORPORATION　Corporate Planning Dept.
5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto 601-8105
Telephone number : 075-692-0251

Corporate Overview



Profile of TOWAPPY

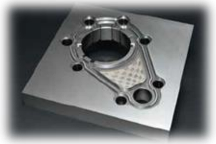
[1] Name: TOWAPPY
[2] Origin of the name:
Delivering happiness to the world from TOWA.
[3] Favorite word: Challenge!

Company name	TOWA CORPORATION
Business	Semiconductor Business, New Business, Medical Device Business, Laser Processing Machines Business
Address	5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto
Established	April 1979
Chairman & CEO	Hirokazu Okada
President Executive Officer	Muneo Miura
Number of Employee	2,166 (consolidated) [as of June 2025]
Paid-in Capital	8.9 billion yen
Code Number	6315

TOWA’s Business

New Business

- TSS
  (Total Solution Service)
- Tools for precision process,
  Consignment processing
- Fine process
- Coating



Consignment processing

Remodeling, Repair,
Preventative Maintenance

Fine process
technology

Tool (end mill)

Medical Device Business

- Fine plastic products
- Medical products

Component for IV drip

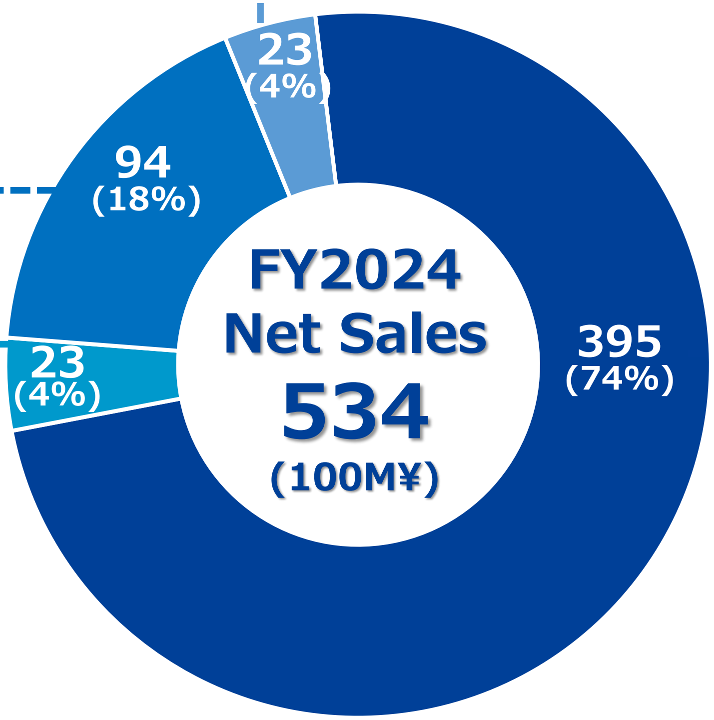
Component for syringe

Laser Processing Machines Business

- Laser Trimmer
- Wafer Marker
- Laser Welder

Laser Trimmer
Model SL432R

Wafer Marker
Model SL473GS3



Semiconductor Business

- Precision molds, Molding equipment and Singulation equipment for semiconductor manufacturing

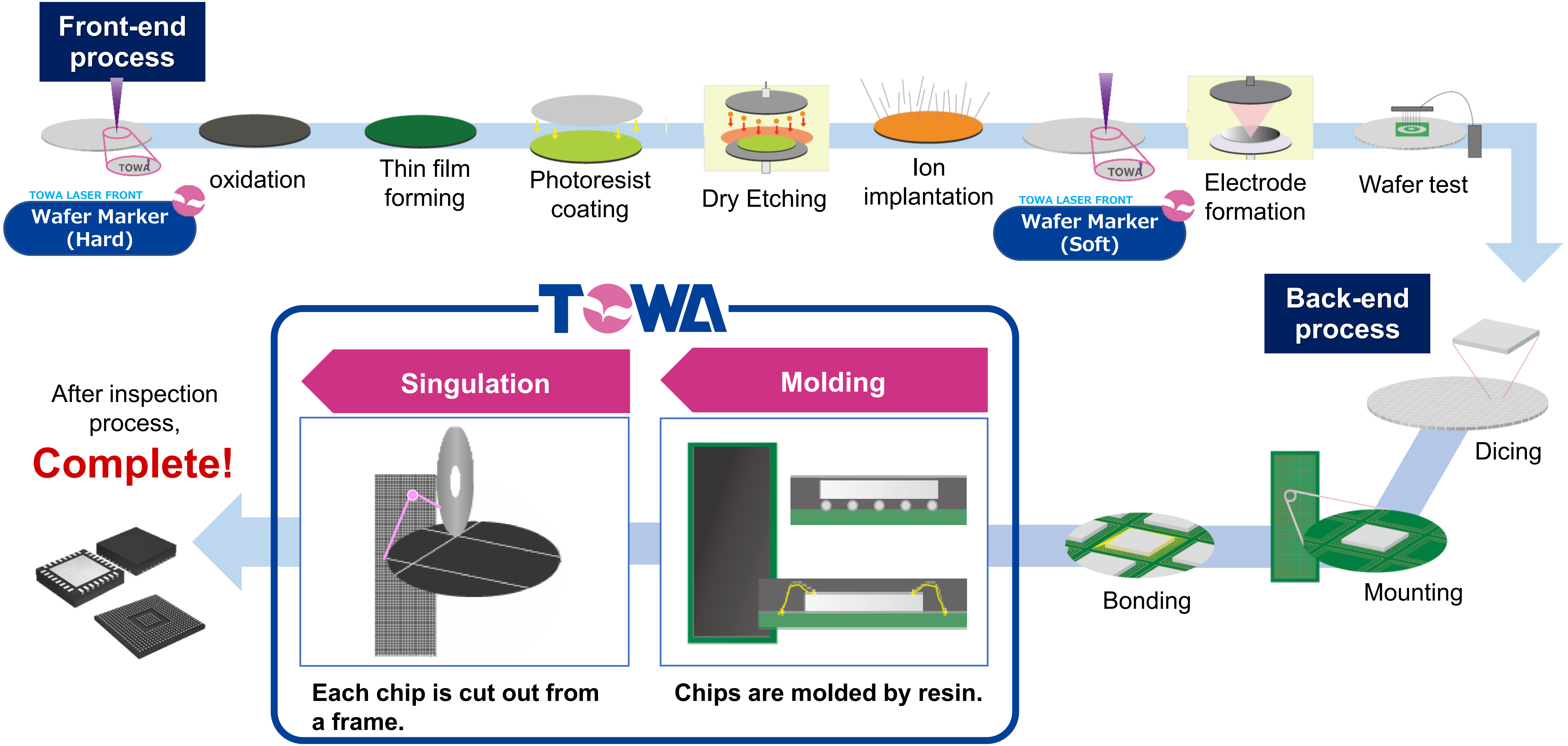
Transfer Mold

Molding Equipment
Model PMC 2030-D

Compression Mold

Molding Equipment
Model CPM 1080

Semiconductor Manufacturing Process



Front-end process

TOWA LASER FRONT
Wafer Marker (Hard)

oxidation

Thin film forming

Photoresist coating

Dry Etching

Ion implantation

TOWA LASER FRONT
Wafer Marker (Soft)

Electrode formation

Wafer test

Back-end process

Dicing

Mounting

Bonding

Molding

Chips are molded by resin.

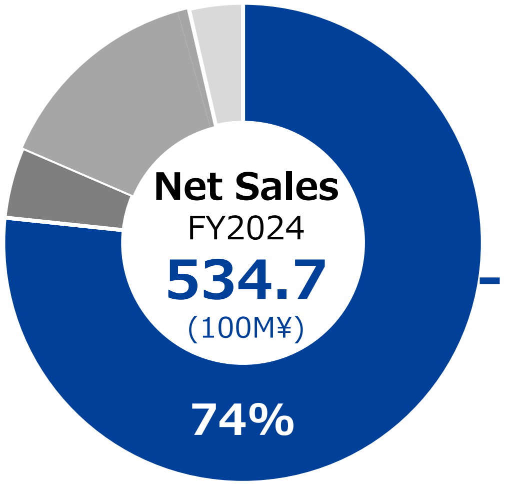
Singulation

Each chip is cut out from a frame.

After inspection process,

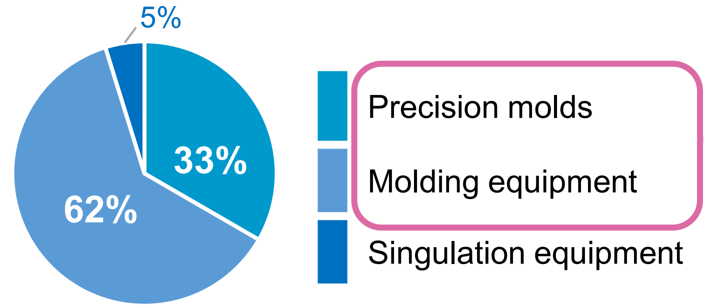
Complete!

Semiconductor Business



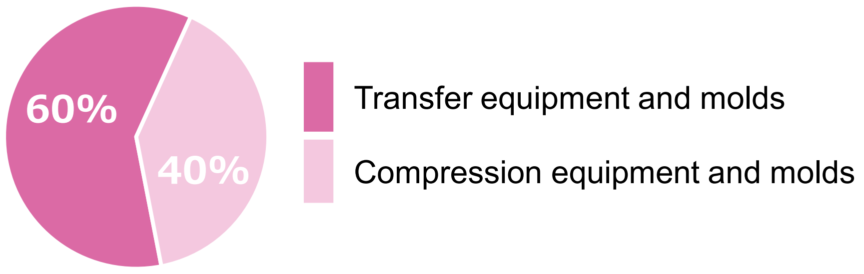
Semiconductor Business

395.3 (100M¥)



Molding equipment and Precision molds

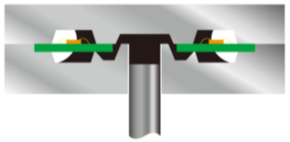
375.9 (100M¥)

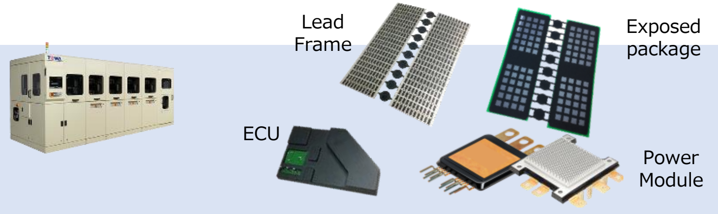


Molding

Transfer Molding

Molding method in which the resin is melted in a pot and filled into a cavity to be hardened.

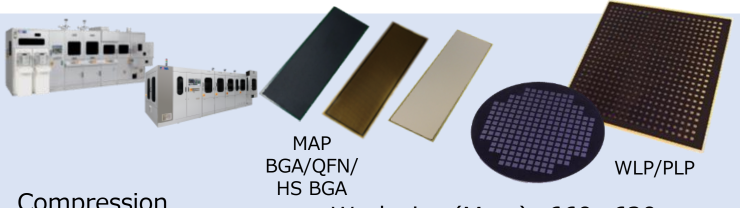




Work size (Max.): 100×300mm

Compression molding

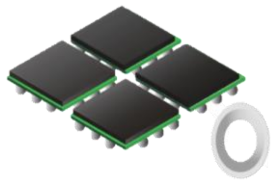
Molding method in which the resin is placed directly into the cavity, and then the workpiece is immersed into the cavity after the resin is melted for resin molding.

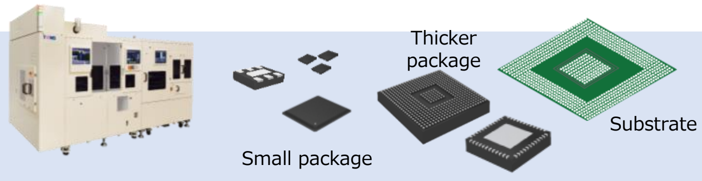


Work size (Max.): 660×620mm

Singulation

Dicing and storing process for molded products by transfer or compression molding methods.





Package size (Min.): 1×1 mm

New Business

Create new market and develop new business

TSS Business

(Total Solution Service)

Propose kinds of solutions such as after sales service, refurbishment, fixing of TOWA's semiconductor manufacturing equipment and used equipment sales.

All molding process all over the world to TOWA!!

- **Life Extension Program**
- **Used equipment sales**
- **Prevention & Upkeep (year to year basis contract)**
- **Parts provision**
- **Training Center**

Coating Business

Apply TOWA's original mold surface processing technologies to medical products and domestic articles.

Expand share in pill pressing machine

Expand share in glass products

Nano tech Business

Apply ultra precise and fine processing technology used in ultra precision mold processing to medical and automobile fields.

Develop products in bacteria cultivation business

Develop lenses for Head Up Display

Develop lens for air picture projection

Tooling Business

Sell tools developed in house and incorporate TOWA's know-how as a mold manufacturer.

CBN・Ultra hard end mill

Processing by undertaking customer order

Fusion of a 3D printer and TOWA's too

Medical Device Business

Company Name	BANDICK CORPORATION
Business	Manufacturing of medical plastic molded products Assembly of medical equipment
Address	596-146 Shimojo Minamiwari, Tatsuoka-cho, Nirasaki-shi, Yamanashi
Acquisition Date	November 18, 1983
President & CEO	Toshihiro Terauchi
Number of Employees	92（as of June 2025)

Main Products

Medical plastic molded product

Plastic molding process using ultra-precision mold technology and proprietary technology

Assembling and production in a clean room

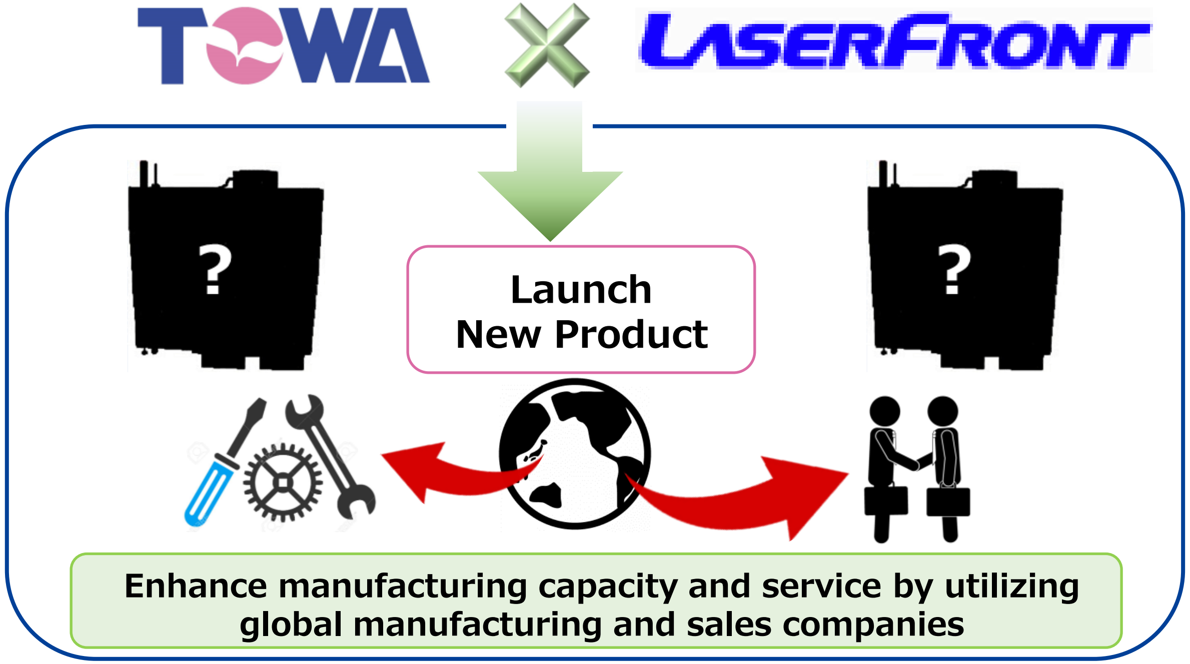
Laser processing machine business

Company Name	TOWA LASERFRONT Corporation	**President & CEO**	Noboru Hayasaka
Business	Development, Design, Manufacturing, Sales and Maintenance of Laser & Laser Processing machines	**Number of Employees**	107（as of June 2025)
Address	1120, Shimokuzawa, Chuo-ku, Sagamihara-shi, Kanagawa		
Acquisition Date	August 1, 2018		

Main Products

Laser Trimmer	Wafer Marker	Laser Welder
		

Combine laser related technology and back-end semiconductor technology to create new market



Launch New Product

Enhance manufacturing capacity and service by utilizing global manufacturing and sales companies

Factories

- ●TOWA
- ● Affiliated Companies

Korea

●TOWA KOREA Co., Ltd.
» Manufacturing of equipment, precision mold and component

●TOWA FINE Co., Ltd.
»Manufacturing of blade

China

●TOWA (Suzhou) Co., Ltd.
»Manufacturing of equipment and precision mold

●TOWA (Nantong) Co., Ltd.
»Manufacturing of equipment and precision mold

Malaysia

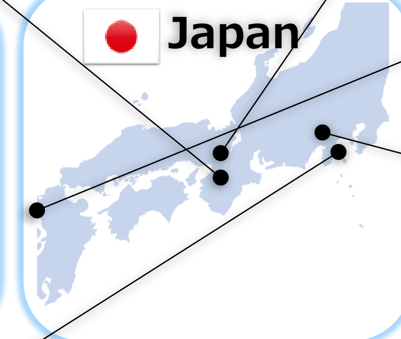
●TOWAM Sdn. Bhd.
»Manufacturing of equipment

●TOWA TOOL Sdn. Bhd.
»Manufacturing of mold

Kyoto (Kyoto-shi)

●Headquarters/Factory
»Develop/manufacture of equipment and precision mold

Japan



Kyoto (Ujitawara-cho)

●Kyoto East Plant
»Manufacturing of mold

Saga (Tosu-shi)

●Kyushu Work
» Manufacturing of mold

Yamanashi (Nirasaki-shi)

●BANDICK Corporation
»Manufacturing of fine plastic products

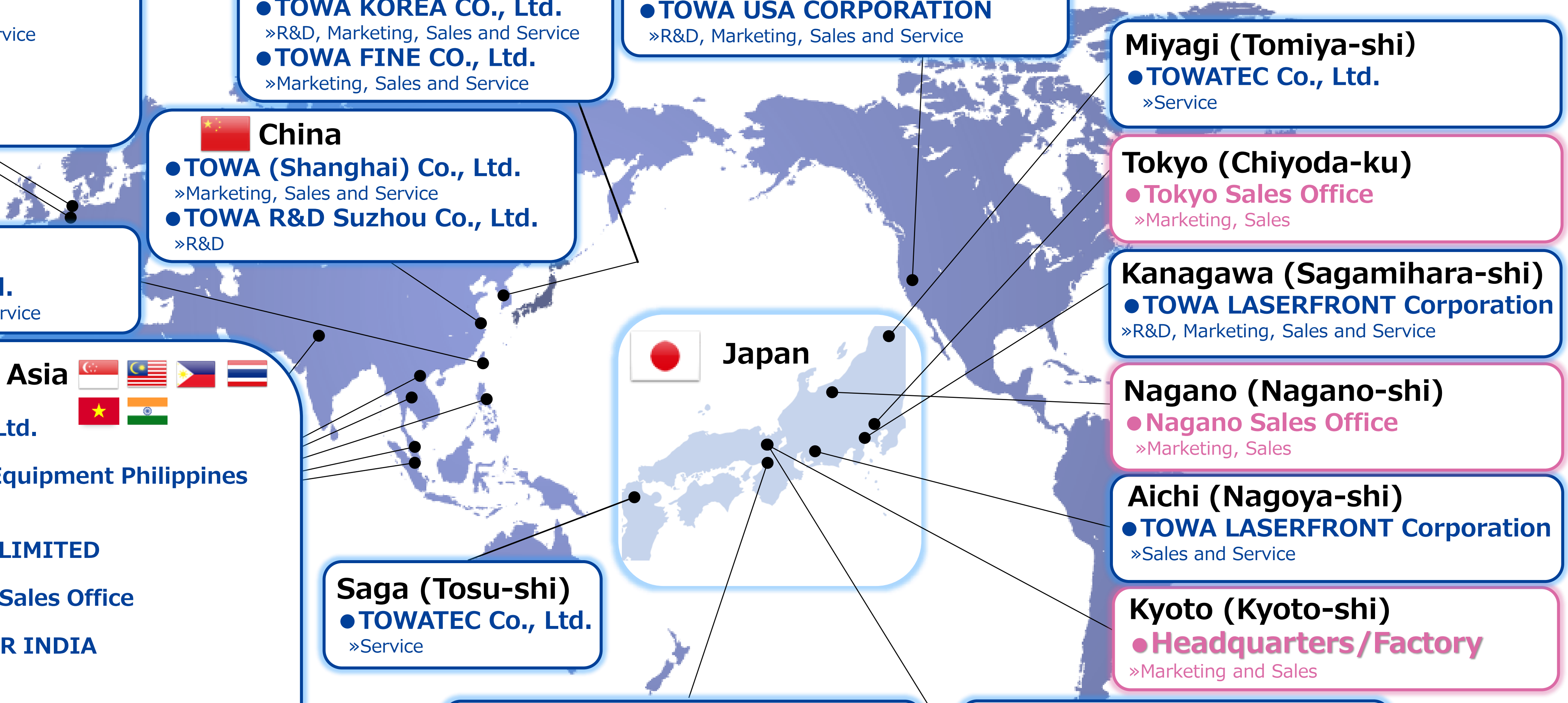
Kanagawa (Sagamihara-shi)

●TOWA LASERFRONT Corporation
»Develop/manufacture of laser & laser processing machines

Sales/Service facility

●TOWA

● Affiliated Companies



Netherlands

●**TOWA Europe B.V.**

»R&D, Marketing, Sales and Service

Germany

●**TOWA Europe GmbH**

»Marketing, Sales and Service

Korea

●**TOWA KOREA CO., Ltd.**

»R&D, Marketing, Sales and Service

●**TOWA FINE CO., Ltd.**

»Marketing, Sales and Service

North America

●**TOWA USA CORPORATION**

»R&D, Marketing, Sales and Service

China

●**TOWA (Shanghai) Co., Ltd.**

»Marketing, Sales and Service

●**TOWA R&D Suzhou Co., Ltd.**

»R&D

Taiwan

●**TOWA Taiwan Co., Ltd.**

» R&D, Marketing, Sales and Service

India & Southeast Asia

»Marketing, Sales and Service

●**TOWA Asia-Pacific Pte.Ltd.**

Singapore, Malaysia

●**TOWA Semiconductor Equipment Philippines Corp.**

Philippines

●**TOWA THAI COMPANY LIMITED**

Thailand

●**TOWA KOREA Vietnam Sales Office**

Vietnam

●**TOWA SEMICONDUCTOR INDIA PRIVATE LIMITED**

INDIA

●**TOWA MALAYSIA SALES & SERVICES SDN. BHD.**

Malaysia

Japan

Miyagi (Tomiya-shi)

●**TOWATEC Co., Ltd.**

»Service

Tokyo (Chiyoda-ku)

●**Tokyo Sales Office**

»Marketing, Sales

Kanagawa (Sagamihara-shi)

●**TOWA LASERFRONT Corporation**

»R&D, Marketing, Sales and Service

Nagano (Nagano-shi)

●**Nagano Sales Office**

»Marketing, Sales

Aichi (Nagoya-shi)

●**TOWA LASERFRONT Corporation**

»Sales and Service

Kyoto (Kyoto-shi)

●**Headquarters/Factory**

»Marketing and Sales

Saga (Tosu-shi)

●**TOWATEC Co., Ltd.**

»Service

Osaka (Osaka-shi)

●**TOWA LASERFRONT Corporation**

»Sales and Service

Kyoto (Kyoto-shi)

●**TOWATEC Co., Ltd.**

»Service

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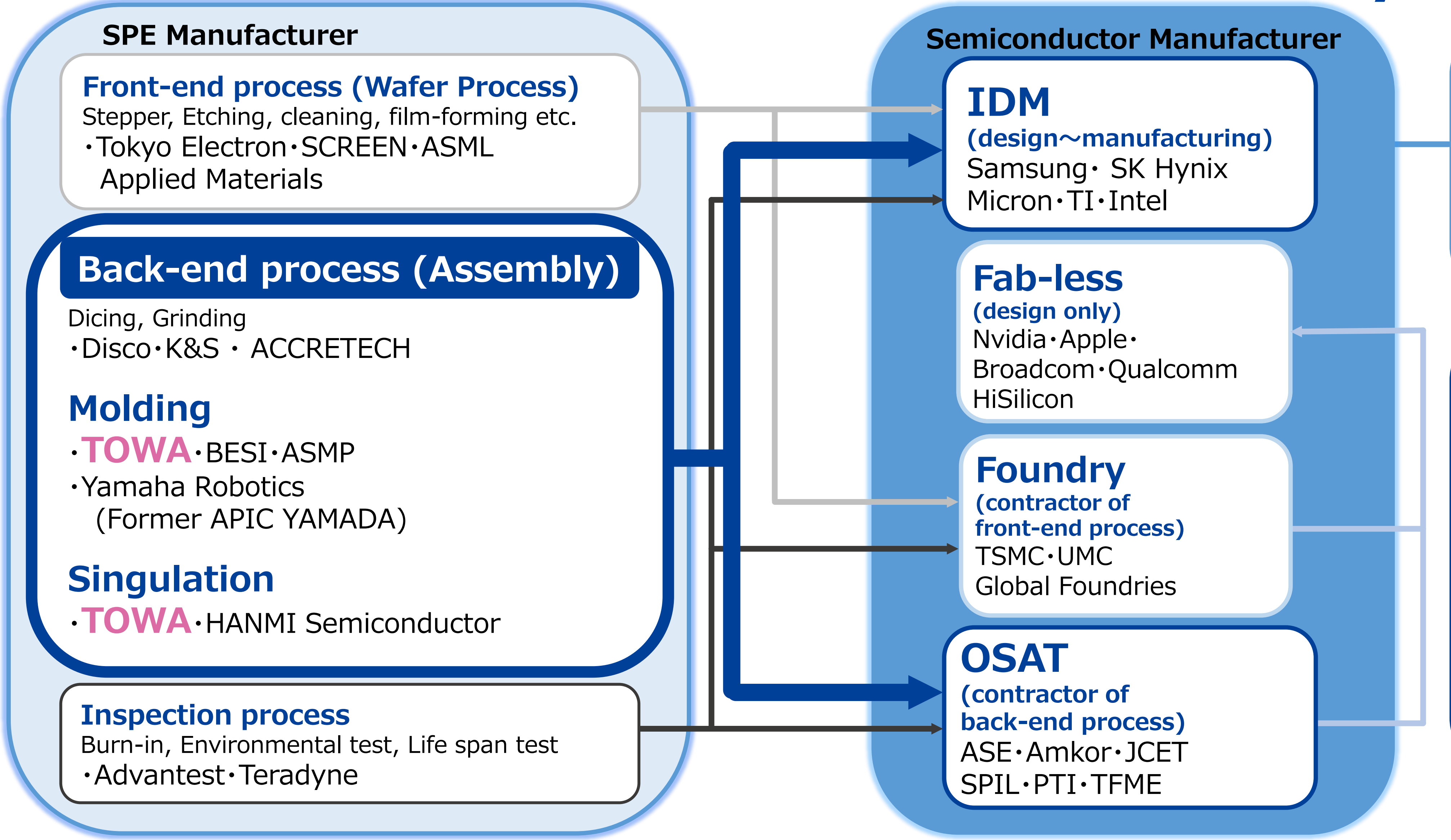
Interrelation of Semiconductor Industry



SPE Manufacturer

Front-end process (Wafer Process)
Stepper, Etching, cleaning, film-forming etc.
・Tokyo Electron・SCREEN・ASML
Applied Materials

Back-end process (Assembly)

Dicing, Grinding
・Disco・K&S ・ ACCRETECH

Molding
・**TOWA**・BESI・ASMP
・Yamaha Robotics
(Former APIC YAMADA)

Singulation
・**TOWA**・HANMI Semiconductor

Inspection process
Burn-in, Environmental test, Life span test
・Advantest・Teradyne

Semiconductor Manufacturer

IDM
(design～manufacturing)
Samsung・ SK Hynix
Micron・TI・Intel

Fab-less
(design only)
Nvidia・Apple・
Broadcom・Qualcomm
HiSilicon

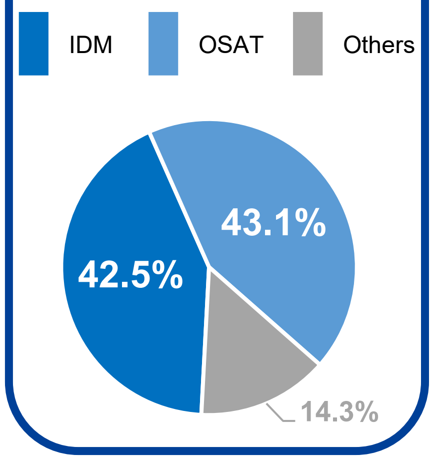
Foundry
(contractor of front-end process)
TSMC・UMC
Global Foundries

OSAT
(contractor of back-end process)
ASE・Amkor・JCET
SPIL・PTI・TFME

Products Manufacturer
(End User)

Apple・Samsung
Huawei・Sony
Xiaomi・OPPO
(ex) smartphones

Net Sales Portion by Customer
(FY 2024)

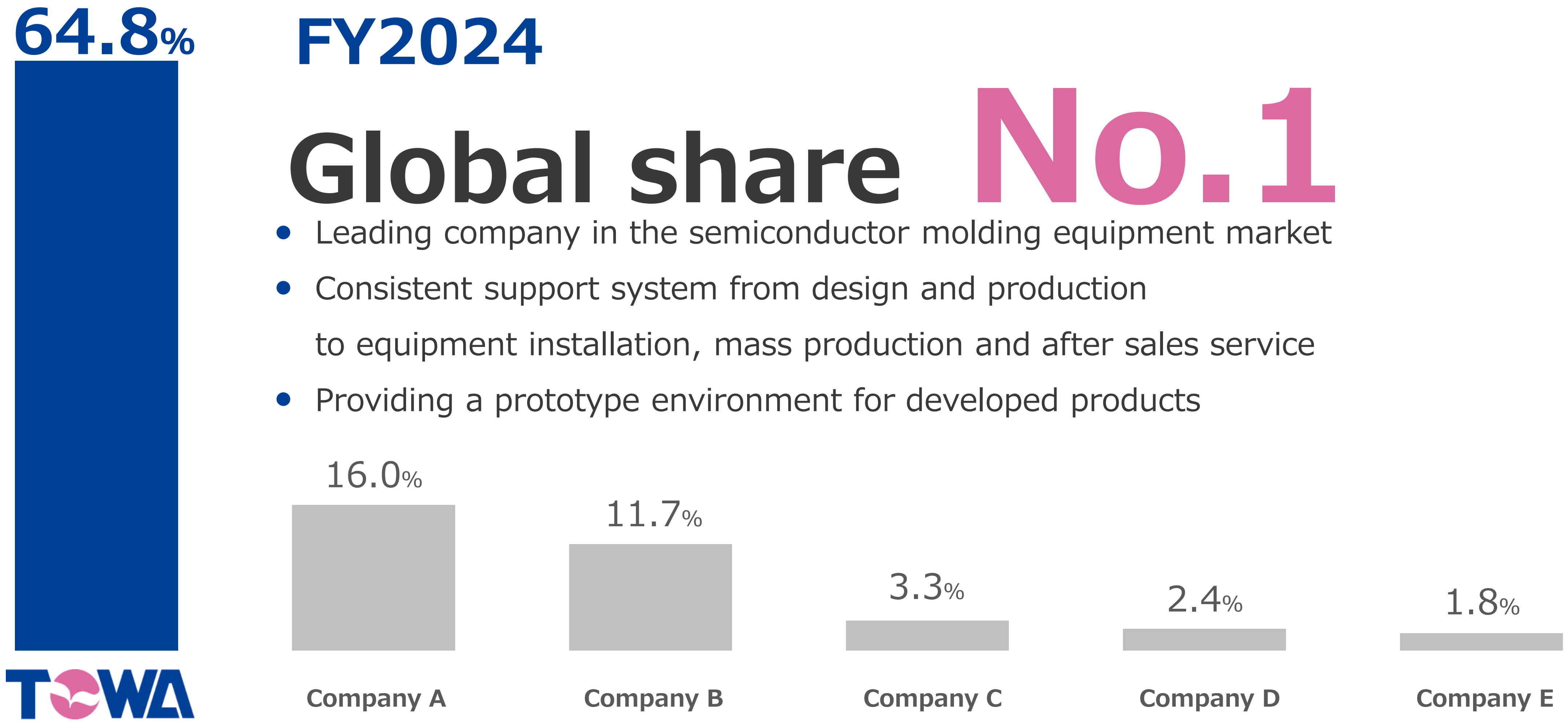


Global share of semiconductor molding equipment

FY2024

Global share No.1

- Leading company in the semiconductor molding equipment market
- Consistent support system from design and production
  to equipment installation, mass production and after sales service
- Providing a prototype environment for developed products



*Created by our company based on data from TechInsights

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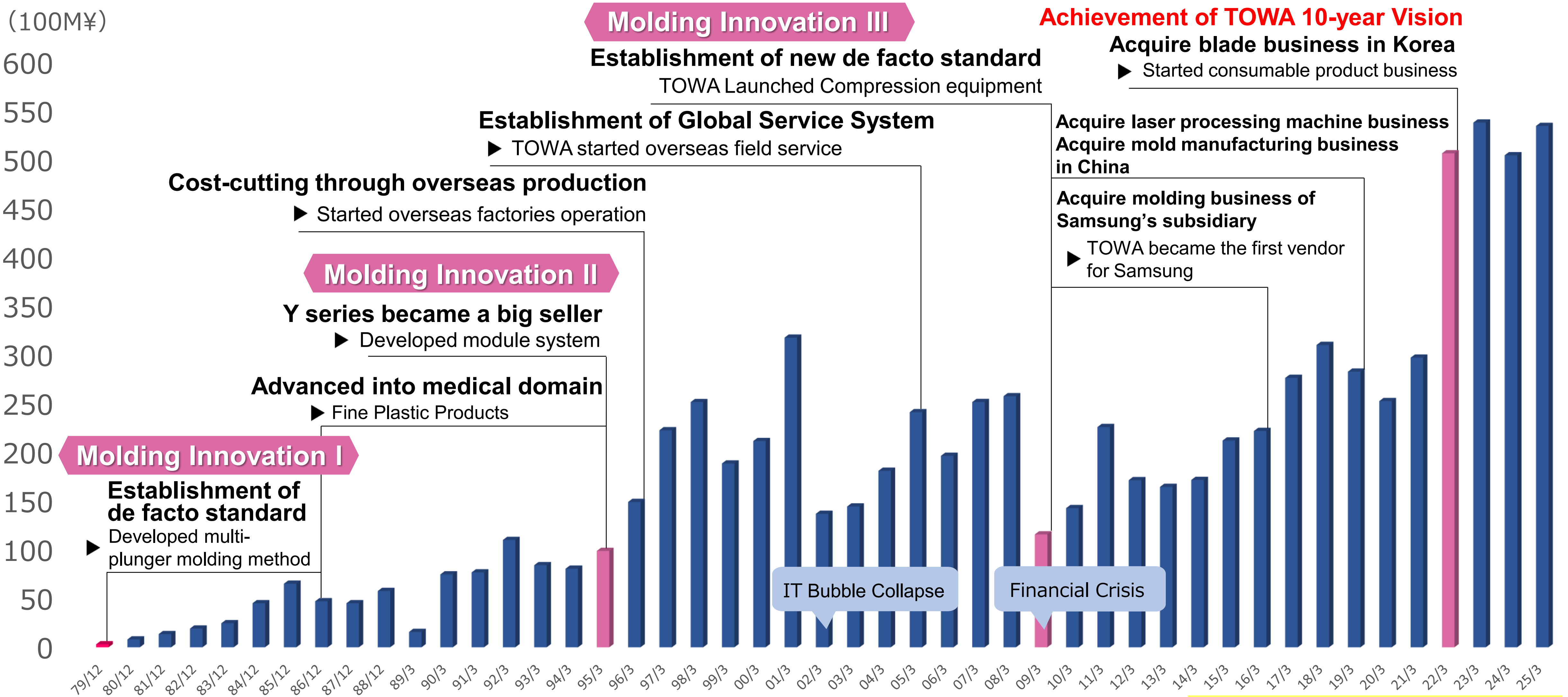
Progress of TOWA



Molding Innovation I

Establishment of de facto standard

▶ Developed multi-plunger molding method

Advanced into medical domain

▶ Fine Plastic Products

Molding Innovation II

Y series became a big seller

▶ Developed module system

Cost-cutting through overseas production

▶ Started overseas factories operation

Establishment of Global Service System

▶ TOWA started overseas field service

Molding Innovation III

Establishment of new de facto standard

TOWA Launched Compression equipment

IT Bubble Collapse

Financial Crisis

Acquire molding business of Samsung's subsidiary

▶ TOWA became the first vendor for Samsung

Acquire laser processing machine business
Acquire mold manufacturing business in China

Achievement of TOWA 10-year Vision

Acquire blade business in Korea

▶ Started consumable product business

Apr, 1979
Established

Sep, 1996
Listed on Osaka Securities Exchange

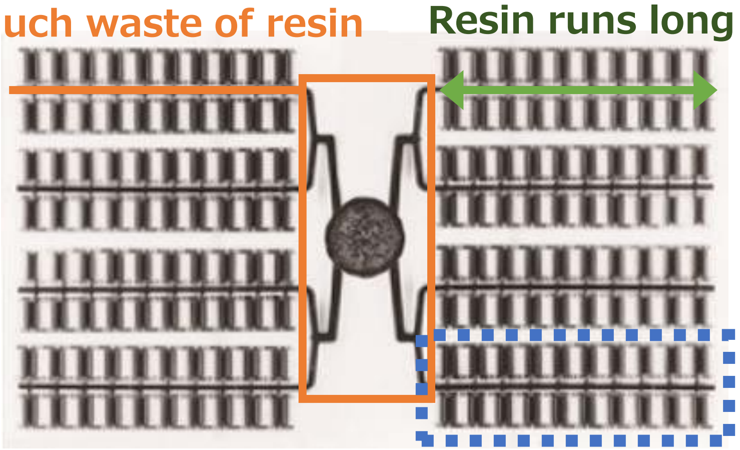
Nov, 2000
Listed on Tokyo Stock Exchange

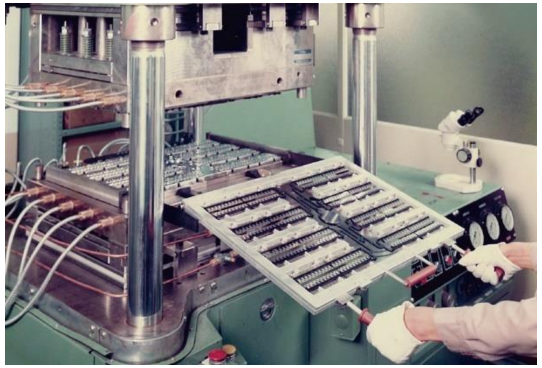
Mar, 2022
Announcement of TOWA Vision 2032

Molding innovation I (1979)

Conventional Mold

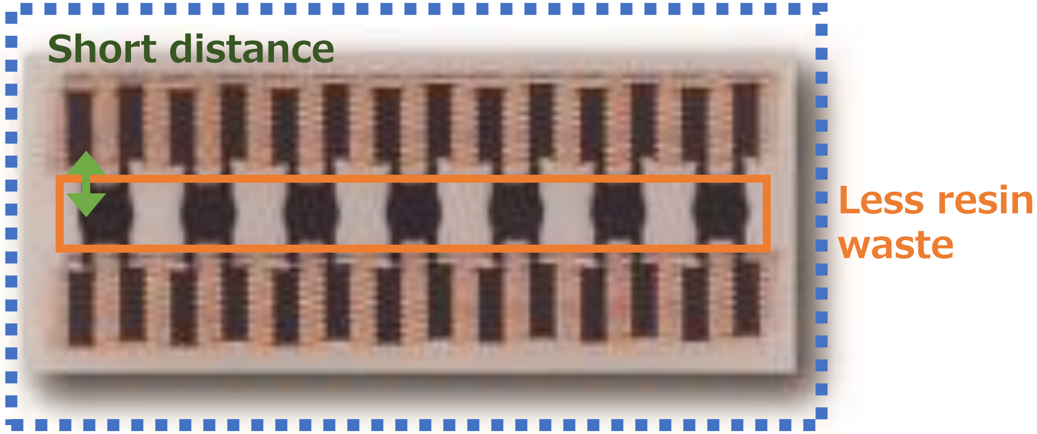
Manual molding by putting one palm size resin into the central pod. Resin runs **long distance**. Molding quality is **not homogeneous**. And **much waste of resin**.





Multi-Plunger Mold

Auto molding by putting finger size resins into several pods. This realized **short** runner, **homogeneous** molding quality and **less waste of resin**.



Molding innovation II (1995)

Module System (Y series)

**Before the development of Module System,
Molding equipment was･･･**

Each equipment is designed depends on what or how much it will manufacture.
Semiconductor manufacturers had to buy another equipment ,
when they want to manufacture another type of product or increase their product volume.

2 Module Connection

Module System enables to adjust press number!!

- Even you have only one Y series machine,
  you can manufacture many types of products or increase your product volume.

4 Module Connection

Y series is sufficient to meet the needs of assembly subcontractor, to perform backend process bringing from IDM.

Semiconductor molding equipment is one of the strongest quality of TOWA.

Molding innovation III (2009)

Compression Molding Equipment

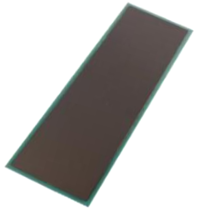
Independent compression molding technology has enabled to mold cutting-edge devices, and cut the cost significantly!!

The compression technology is unrivaled from its launch in 2009 because of the patent and technical difficulty.

Features

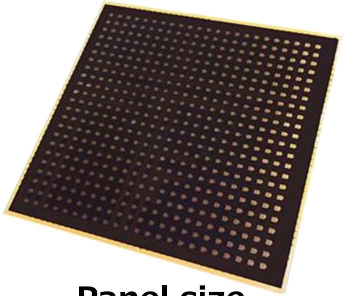
- 100% resin efficiency (CO2 emissions reduced by about 70%)
- Compression molding with no resin fluidity (reduce defective products)
- Most suitable for cutting-edge such as memory and 5G
- Applicable to both granular type and liquid type resin
- Applicable to both panel size and wafer size

Compression Equipment
Model PMC 2030-D



Substrate size
100×300mm

Wafer size
φ300mm



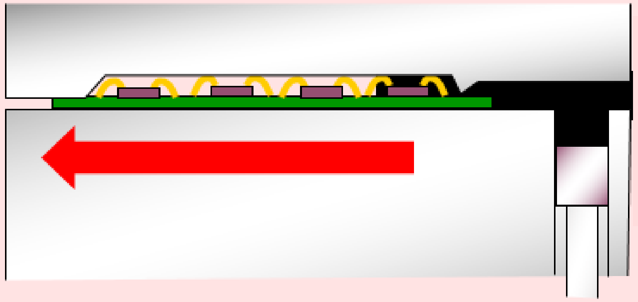
Panel size
600mm×600mm

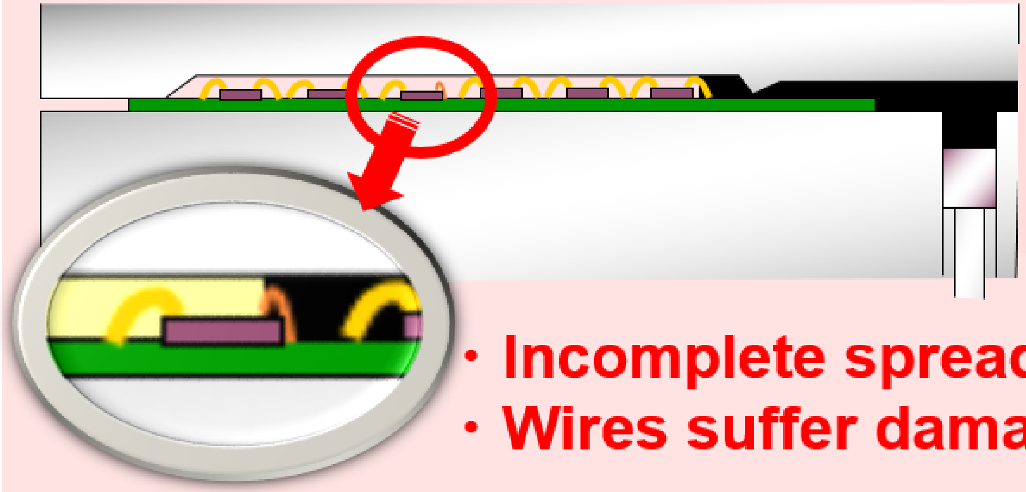
Encapsulation (Molding) Process

Transfer molding

Injecting resin type

Resin flows



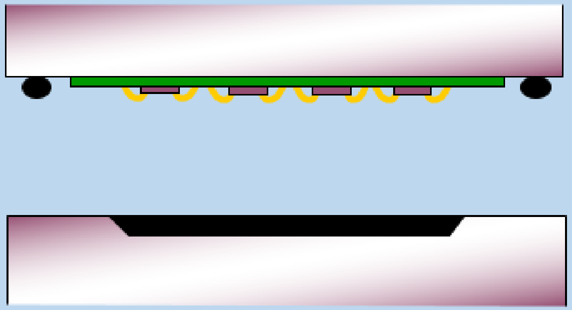


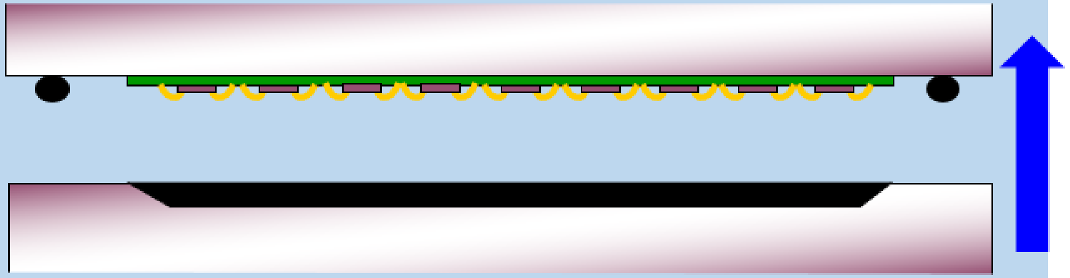
- Incomplete spreading
- Wires suffer damage

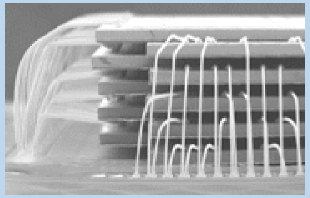
Compression molding

Compressing resin type

No Resin fluidity







- TOWA enabled large size panel molding
- No damage to products

Semiconductor Manufacturing Equipment Line-Up

～Compression Mold～

Compression Equipment

Model CPM 1180

Work max size：660×620mm

Compression Equipment

Model CPM 1080

Work max size：φ300mm, 320x320mm

Compression Equipment

Model PMC 2030-D

Work max size：100x300mm

～ Transfer Mold～

Transfer Equipment

Model YPM 1180

Work max size：100x300mm

Transfer Equipment

Model YPM1250-EPQ

Work max size：□150mm, 100x300mm

～ Singulation～

Singulation Equipment

Model FMS 4040

Work max size：100x300mm